## Travel Grant Application (ECS) San Francisco, CA

The Society's Battery, Corrosion, Dielectric, Electrodesposition, Electronics and Photonics, Energy Technology, High Temperature Materials (HTM), Industrial Electrochemistry and Electrochemical Engineering (IEEE), Organic and Biological Electrochemistry (OBE), Physical and Analytical Electrochemistry, and Sensor Divisions offer travel grants to students presenting papers at the Society's next meeting, in San Francisco, CA May 24-29, 2009. To apply, complete this application and send it along with a copy of your transcript and a letter from an involved faculty member attesting both to the quality of the student's work and financial needs, and a copy of the student's meeting abstract. For additional information please contact the Division contact below, as requirements might differ between Divisions.

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Name:								
School Adress:								
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Undergraduate Year (U) or Graduate Year (G) - circle one:	U3	U4	G1	G2	G3	G4	G5	
	out of possible:							
(please provide a letter of recommendation from your faculty advisor and a co	opy of your tr	anscript)						
Symposium Title (#):								
Title of paper to be presented at the meeting:								
Are you an ECS Student Member of the Society? (if not, please additionally submit the Awarded Student Membership applications)		⊒ yes		l no				
Estimated meeting expenditures: \$								
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Check Division under which award is being applied for: (A	Application	ns made to	o multiple	Divisions	will be re	ejected)		
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☐ Dielectric Science & Technology-Send to: H. Rathore, IBM, Interest. E-mail: rathore@us.ibm.com	nal Mail Sto	p AE1,B/64	0, 2070 Rte	52, Hopew	ell Junction	n, NY 12533	, USA.	
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Applications for Travel Grants for the San Francisco, CA meeting must be received no later than December 15, 2008.